

SOT895-1

plastic flanged cavity package; 2 mounting slots; 2 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFM2
Package type industry code	DFM2
Package style descriptive code	DFM (double-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	F (flange mount)
Issue date	21-2-2006

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		19.7	-	19.8	19.9	mm
E	package width		9.27	-	9.4	9.53	mm
A	seated height		3.3	-	3.7	4.1	mm
n ₂	actual quantity of termination		-	-	2	-	



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2. Package outline

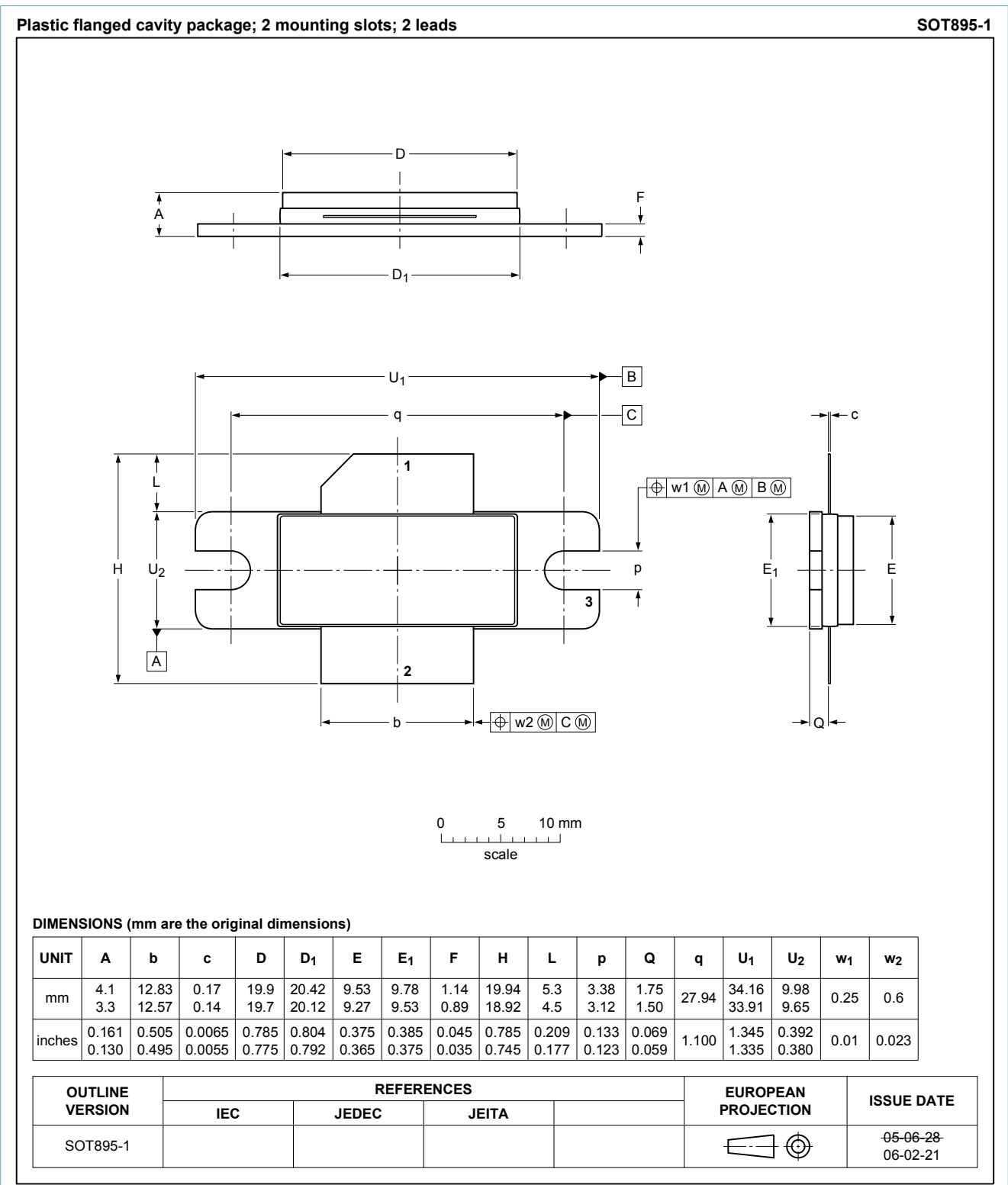


Fig. 1. Package outline DFM2 (SOT895-1)

3. Legal information

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